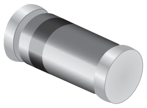
Material Composition Specification

SOD-80 Case



Device average mass . . . . **28 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.11%	0.03	Si	7440-21-3	0.11%	0.03	1,071
leadframe	Fe alloy w/ silver plating	56.32%	15.77	Cu	7440-50-8	8.93%	2.5	89,286
				Fe	7439-89-6	23.93%	6.7	239,286
				Ni	7440-02-0	21.07%	5.9	210,714
				Ag	7440-22-4	2.39%	0.67	23,929
encapsulation	glass	40.0%	11.2	SiO_2	7631-86-9	16.96%	4.75	169,643
				Pb	7439-92-1	23.04%	6.45	230,357
plating*	tin/lead process	3.57%	1.0	Sn	7440-31-5	2.86%	0.8	28,571
				Pb	7439-92-1	0.71%	0.2	7,143
	matte tin	3.57%	1.0	Sn	7440-31-5	3.57%	1.0	35,714

*For Lead Free plating, add suffix "PB FREE" to part number.
For Tin/Lead plating, add suffix "TIN/LEAD" to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

R5 (16-July 2018)